

# Global Flip Chip Bonder Market by Size, by Type, by Application, by Region, History and Forecast 2019-2030

<https://marketpublishers.com/r/GA7FBECB2CA3EN.html>

Date: April 2024

Pages: 133

Price: US\$ 3,950.00 (Single User License)

ID: GA7FBECB2CA3EN

## Abstracts

Flip chip is a method used for components or devices that can be bonded directly onto a substrate, board or carrier face-down. The connection is made through conductive bumps placed on the surface of the die. The placing process amounts to the following:

1. Die is picked up and place on a 'flipping device'
2. Die is 'flipped' and moved to hover over the substrate (or board or carrier) where bumps reside - precisely positioned in their previously defined positions
3. The tool then places the die on the bump with a programmed amount of force

Flip chip bumping is a vital step to the process. The bump provides the necessary electrical connection between the die and the substrate, provides thermal conduction through the two materials, acts as a 'spacer' to prevent electrical shorts and provides mechanical support.

Flip chips avoid wire bonding and therefore are able to be much smaller than their counterparts. Flip chip processes have been around for more than 40 years. Since then, thousands of applications have taken advantage of the size and cost benefits enabled by the flip chip assembly method.

According to APO Research, The global Flip Chip Bonder market is projected to grow from US\$ million in 2024 to US\$ million by 2030, at a Compound Annual Growth Rate (CAGR) of % during the forecast period.

Global Flip Chip Bonder key players include Besi, ASM Pacific Technology, Shibaura, Kulicke & Soffa, etc. Global top four manufacturers hold a share nearly 70%.

China is the largest market, with a share about 25%, followed by United States, and Taiwan, both have a share about 30 percent.

In terms of product, Fully Automatic is the largest segment, with a share over 75%. And in terms of application, the largest application is IDMs, followed by OSAT.

In terms of production side, this report researches the Flip Chip Bonder production, growth rate, market share by manufacturers and by region (region level and country level), from 2019 to 2024, and forecast to 2030.

In terms of consumption side, this report focuses on the sales of Flip Chip Bonder by region (region level and country level), by company, by type and by application. from 2019 to 2024 and forecast to 2030.

This report presents an overview of global market for Flip Chip Bonder, capacity, output, revenue and price. Analyses of the global market trends, with historic market revenue or sales data for 2019 - 2023, estimates for 2024, and projections of CAGR through 2030.

This report researches the key producers of Flip Chip Bonder, also provides the consumption of main regions and countries. Of the upcoming market potential for Flip Chip Bonder, and key regions or countries of focus to forecast this market into various segments and sub-segments. Country specific data and market value analysis for the U.S., Canada, Mexico, Brazil, China, Japan, South Korea, Southeast Asia, India, Germany, the U.K., Italy, Middle East, Africa, and Other Countries.

This report focuses on the Flip Chip Bonder sales, revenue, market share and industry ranking of main manufacturers, data from 2019 to 2024. Identification of the major stakeholders in the global Flip Chip Bonder market, and analysis of their competitive landscape and market positioning based on recent developments and segmental revenues. This report will help stakeholders to understand the competitive landscape and gain more insights and position their businesses and market strategies in a better way.

This report analyzes the segments data by type and by application, sales, revenue, and price, from 2019 to 2030. Evaluation and forecast the market size for Flip Chip Bonder sales, projected growth trends, production technology, application and end-user

industry.

Descriptive company profiles of the major global players, including BESI, ASMPT, Shibaura, Muehlbauer, K&S, Hamni, AMICRA Microtechnologies, SET and Athlete FA, etc.

#### Flip Chip Bonder segment by Company

BESI

ASMPT

Shibaura

Muehlbauer

K&S

Hamni

AMICRA Microtechnologies

SET

Athlete FA

#### Flip Chip Bonder segment by Type

Fully Automatic

Semi-Automatic

#### Flip Chip Bonder segment by Application

IDMs

OSAT

## Flip Chip Bonder segment by Region

North America

U.S.

Canada

Europe

Germany

France

U.K.

Italy

Russia

Asia-Pacific

China

Japan

South Korea

India

Australia

China Taiwan

Indonesia

Thailand

Malaysia

Latin America

Mexico

Brazil

Argentina

Middle East & Africa

Turkey

Saudi Arabia

UAE

## Study Objectives

1. To analyze and research the global status and future forecast, involving, production, value, consumption, growth rate (CAGR), market share, historical and forecast.
2. To present the key manufacturers, capacity, production, revenue, market share, and Recent Developments.
3. To split the breakdown data by regions, type, manufacturers, and Application.
4. To analyze the global and key regions market potential and advantage, opportunity and challenge, restraints, and risks.
5. To identify significant trends, drivers, influence factors in global and regions.
6. To analyze competitive developments such as expansions, agreements, new product launches, and acquisitions in the market.

## Reasons to Buy This Report

1. This report will help the readers to understand the competition within the industries and strategies for the competitive environment to enhance the potential profit. The report also focuses on the competitive landscape of the global Flip Chip Bonder market, and introduces in detail the market share, industry ranking, competitor ecosystem, market performance, new product development, operation situation, expansion, and acquisition. etc. of the main players, which helps the readers to identify the main competitors and deeply understand the competition pattern of the market.
2. This report will help stakeholders to understand the global industry status and trends of Flip Chip Bonder and provides them with information on key market drivers, restraints, challenges, and opportunities.
3. This report will help stakeholders to understand competitors better and gain more insights to strengthen their position in their businesses. The competitive landscape section includes the market share and rank (in volume and value), competitor ecosystem, new product development, expansion, and acquisition.
4. This report stays updated with novel technology integration, features, and the latest developments in the market.
5. This report helps stakeholders to gain insights into which regions to target globally.
6. This report helps stakeholders to gain insights into the end-user perception concerning the adoption of Flip Chip Bonder.
7. This report helps stakeholders to identify some of the key players in the market and understand their valuable contribution.

## Chapter Outline

Chapter 1: Provides an overview of the Flip Chip Bonder market, including product definition, global market growth prospects, production value, capacity, and average price forecasts (2019-2030).

Chapter 2: Analysis key trends, drivers, challenges, and opportunities within the global Flip Chip Bonder industry.

Chapter 3: Detailed analysis of Flip Chip Bonder market competition landscape.

Including Flip Chip Bonder manufacturers' output value, output and average price from 2019 to 2024, as well as competition analysis indicators such as origin, product type, application, merger and acquisition information, etc.

Chapter 4: Provides the analysis of various market segments by type, covering the market size and development potential of each market segment, to help readers find the blue ocean market in different market segments.

Chapter 5: Provides the analysis of various market segments by application, covering the market size and development potential of each market segment, to help readers find the blue ocean market in different downstream markets.

Chapter 6: Provides profiles of key players, introducing the basic situation of the main companies in the market in detail, including product production/output, value, price, gross margin, product introduction, recent development, etc.

Chapter 7: Production/Production Value of Flip Chip Bonder by region. It provides a quantitative analysis of the market size and development potential of each region in the next six years.

Chapter 8: Consumption of Flip Chip Bonder in regional level and country level. It provides a quantitative analysis of the market size and development potential of each region and its main countries and introduces the market development, future development prospects, market space, and production of each country in the world.

Chapter 9: Analysis of industrial chain, including the upstream and downstream of the industry.

Chapter 10: Concluding Insights of the report.

## Contents

### 1 MARKET OVERVIEW

- 1.1 Product Definition
- 1.2 Global Market Growth Prospects
  - 1.2.1 Global Flip Chip Bonder Production Value Estimates and Forecasts (2019-2030)
  - 1.2.2 Global Flip Chip Bonder Production Capacity Estimates and Forecasts (2019-2030)
  - 1.2.3 Global Flip Chip Bonder Production Estimates and Forecasts (2019-2030)
  - 1.2.4 Global Flip Chip Bonder Market Average Price (2019-2030)
- 1.3 Assumptions and Limitations
- 1.4 Study Goals and Objectives

### 2 GLOBAL FLIP CHIP BONDER MARKET DYNAMICS

- 2.1 Flip Chip Bonder Industry Trends
- 2.2 Flip Chip Bonder Industry Drivers
- 2.3 Flip Chip Bonder Industry Opportunities and Challenges
- 2.4 Flip Chip Bonder Industry Restraints

### 3 FLIP CHIP BONDER MARKET BY MANUFACTURERS

- 3.1 Global Flip Chip Bonder Production Value by Manufacturers (2019-2024)
- 3.2 Global Flip Chip Bonder Production by Manufacturers (2019-2024)
- 3.3 Global Flip Chip Bonder Average Price by Manufacturers (2019-2024)
- 3.4 Global Flip Chip Bonder Industry Manufacturers Ranking, 2022 VS 2023 VS 2024
- 3.5 Global Flip Chip Bonder Key Manufacturers Manufacturing Sites & Headquarters
- 3.6 Global Flip Chip Bonder Manufacturers, Product Type & Application
- 3.7 Global Flip Chip Bonder Manufacturers Commercialization Time
- 3.8 Market Competitive Analysis
  - 3.8.1 Global Flip Chip Bonder Market CR5 and HHI
  - 3.8.2 Global Top 5 and 10 Flip Chip Bonder Players Market Share by Production Value in 2023
  - 3.8.3 2023 Flip Chip Bonder Tier 1, Tier 2, and Tier

### 4 FLIP CHIP BONDER MARKET BY TYPE

- 4.1 Flip Chip Bonder Type Introduction



- 4.1.1 Fully Automatic
- 4.1.2 Semi-Automatic
- 4.2 Global Flip Chip Bonder Production by Type
  - 4.2.1 Global Flip Chip Bonder Production by Type (2019 VS 2023 VS 2030)
  - 4.2.2 Global Flip Chip Bonder Production by Type (2019-2030)
  - 4.2.3 Global Flip Chip Bonder Production Market Share by Type (2019-2030)
- 4.3 Global Flip Chip Bonder Production Value by Type
  - 4.3.1 Global Flip Chip Bonder Production Value by Type (2019 VS 2023 VS 2030)
  - 4.3.2 Global Flip Chip Bonder Production Value by Type (2019-2030)
  - 4.3.3 Global Flip Chip Bonder Production Value Market Share by Type (2019-2030)

## **5 FLIP CHIP BONDER MARKET BY APPLICATION**

- 5.1 Flip Chip Bonder Application Introduction
  - 5.1.1 IDMs
  - 5.1.2 OSAT
- 5.2 Global Flip Chip Bonder Production by Application
  - 5.2.1 Global Flip Chip Bonder Production by Application (2019 VS 2023 VS 2030)
  - 5.2.2 Global Flip Chip Bonder Production by Application (2019-2030)
  - 5.2.3 Global Flip Chip Bonder Production Market Share by Application (2019-2030)
- 5.3 Global Flip Chip Bonder Production Value by Application
  - 5.3.1 Global Flip Chip Bonder Production Value by Application (2019 VS 2023 VS 2030)
  - 5.3.2 Global Flip Chip Bonder Production Value by Application (2019-2030)
  - 5.3.3 Global Flip Chip Bonder Production Value Market Share by Application (2019-2030)

## **6 COMPANY PROFILES**

- 6.1 BESI
  - 6.1.1 BESI Comapny Information
  - 6.1.2 BESI Business Overview
  - 6.1.3 BESI Flip Chip Bonder Production, Value and Gross Margin (2019-2024)
  - 6.1.4 BESI Flip Chip Bonder Product Portfolio
  - 6.1.5 BESI Recent Developments
- 6.2 ASMPT
  - 6.2.1 ASMPT Comapny Information
  - 6.2.2 ASMPT Business Overview
  - 6.2.3 ASMPT Flip Chip Bonder Production, Value and Gross Margin (2019-2024)

- 6.2.4 ASMPT Flip Chip Bonder Product Portfolio
- 6.2.5 ASMPT Recent Developments
- 6.3 Shibaura
  - 6.3.1 Shibaura Comapny Information
  - 6.3.2 Shibaura Business Overview
  - 6.3.3 Shibaura Flip Chip Bonder Production, Value and Gross Margin (2019-2024)
  - 6.3.4 Shibaura Flip Chip Bonder Product Portfolio
  - 6.3.5 Shibaura Recent Developments
- 6.4 Muehlbauer
  - 6.4.1 Muehlbauer Comapny Information
  - 6.4.2 Muehlbauer Business Overview
  - 6.4.3 Muehlbauer Flip Chip Bonder Production, Value and Gross Margin (2019-2024)
  - 6.4.4 Muehlbauer Flip Chip Bonder Product Portfolio
  - 6.4.5 Muehlbauer Recent Developments
- 6.5 K&S
  - 6.5.1 K&S Comapny Information
  - 6.5.2 K&S Business Overview
  - 6.5.3 K&S Flip Chip Bonder Production, Value and Gross Margin (2019-2024)
  - 6.5.4 K&S Flip Chip Bonder Product Portfolio
  - 6.5.5 K&S Recent Developments
- 6.6 Hamni
  - 6.6.1 Hamni Comapny Information
  - 6.6.2 Hamni Business Overview
  - 6.6.3 Hamni Flip Chip Bonder Production, Value and Gross Margin (2019-2024)
  - 6.6.4 Hamni Flip Chip Bonder Product Portfolio
  - 6.6.5 Hamni Recent Developments
- 6.7 AMICRA Microtechnologies
  - 6.7.1 AMICRA Microtechnologies Comapny Information
  - 6.7.2 AMICRA Microtechnologies Business Overview
  - 6.7.3 AMICRA Microtechnologies Flip Chip Bonder Production, Value and Gross Margin (2019-2024)
  - 6.7.4 AMICRA Microtechnologies Flip Chip Bonder Product Portfolio
  - 6.7.5 AMICRA Microtechnologies Recent Developments
- 6.8 SET
  - 6.8.1 SET Comapny Information
  - 6.8.2 SET Business Overview
  - 6.8.3 SET Flip Chip Bonder Production, Value and Gross Margin (2019-2024)
  - 6.8.4 SET Flip Chip Bonder Product Portfolio
  - 6.8.5 SET Recent Developments

## 6.9 Athlete FA

6.9.1 Athlete FA Company Information

6.9.2 Athlete FA Business Overview

6.9.3 Athlete FA Flip Chip Bonder Production, Value and Gross Margin (2019-2024)

6.9.4 Athlete FA Flip Chip Bonder Product Portfolio

6.9.5 Athlete FA Recent Developments

## 7 GLOBAL FLIP CHIP BONDER PRODUCTION BY REGION

7.1 Global Flip Chip Bonder Production by Region: 2019 VS 2023 VS 2030

7.2 Global Flip Chip Bonder Production by Region (2019-2030)

7.2.1 Global Flip Chip Bonder Production by Region: 2019-2024

7.2.2 Global Flip Chip Bonder Production by Region (2025-2030)

7.3 Global Flip Chip Bonder Production by Region: 2019 VS 2023 VS 2030

7.4 Global Flip Chip Bonder Production Value by Region (2019-2030)

7.4.1 Global Flip Chip Bonder Production Value by Region: 2019-2024

7.4.2 Global Flip Chip Bonder Production Value by Region (2025-2030)

7.5 Global Flip Chip Bonder Market Price Analysis by Region (2019-2024)

7.6 Regional Production Value Trends (2019-2030)

7.6.1 North America Flip Chip Bonder Production Value (2019-2030)

7.6.2 Europe Flip Chip Bonder Production Value (2019-2030)

7.6.3 Asia-Pacific Flip Chip Bonder Production Value (2019-2030)

7.6.4 Latin America Flip Chip Bonder Production Value (2019-2030)

7.6.5 Middle East & Africa Flip Chip Bonder Production Value (2019-2030)

## 8 GLOBAL FLIP CHIP BONDER CONSUMPTION BY REGION

8.1 Global Flip Chip Bonder Consumption by Region: 2019 VS 2023 VS 2030

8.2 Global Flip Chip Bonder Consumption by Region (2019-2030)

8.2.1 Global Flip Chip Bonder Consumption by Region (2019-2024)

8.2.2 Global Flip Chip Bonder Consumption by Region (2025-2030)

8.3 North America

8.3.1 North America Flip Chip Bonder Consumption Growth Rate by Country: 2019 VS 2023 VS 2030

8.3.2 North America Flip Chip Bonder Consumption by Country (2019-2030)

8.3.3 U.S.

8.3.4 Canada

8.4 Europe

8.4.1 Europe Flip Chip Bonder Consumption Growth Rate by Country: 2019 VS 2023

## VS 2030

### 8.4.2 Europe Flip Chip Bonder Consumption by Country (2019-2030)

#### 8.4.3 Germany

#### 8.4.4 France

#### 8.4.5 U.K.

#### 8.4.6 Italy

#### 8.4.7 Netherlands

## 8.5 Asia Pacific

### 8.5.1 Asia Pacific Flip Chip Bonder Consumption Growth Rate by Country: 2019 VS 2023 VS 2030

#### 8.5.2 Asia Pacific Flip Chip Bonder Consumption by Country (2019-2030)

#### 8.5.3 China

#### 8.5.4 Japan

#### 8.5.5 South Korea

#### 8.5.6 Southeast Asia

#### 8.5.7 India

#### 8.5.8 Australia

## 8.6 LAMEA

### 8.6.1 LAMEA Flip Chip Bonder Consumption Growth Rate by Country: 2019 VS 2023 VS 2030

#### 8.6.2 LAMEA Flip Chip Bonder Consumption by Country (2019-2030)

#### 8.6.3 Mexico

#### 8.6.4 Brazil

#### 8.6.5 Turkey

#### 8.6.6 GCC Countries

## 9 VALUE CHAIN AND SALES CHANNELS ANALYSIS

### 9.1 Flip Chip Bonder Value Chain Analysis

#### 9.1.1 Flip Chip Bonder Key Raw Materials

#### 9.1.2 Raw Materials Key Suppliers

#### 9.1.3 Manufacturing Cost Structure

#### 9.1.4 Flip Chip Bonder Production Mode & Process

### 9.2 Flip Chip Bonder Sales Channels Analysis

#### 9.2.1 Direct Comparison with Distribution Share

#### 9.2.2 Flip Chip Bonder Distributors

#### 9.2.3 Flip Chip Bonder Customers

## 10 CONCLUDING INSIGHTS

## **11 APPENDIX**

11.1 Reasons for Doing This Study

11.2 Research Methodology

11.3 Research Process

11.4 Authors List of This Report

11.5 Data Source

11.5.1 Secondary Sources

11.5.2 Primary Sources

11.6 Disclaimer

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